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DTA114EE(MS)

Product specification

Digital Transistor (Built-in Resistors)
PNP Silicon Surface Mount Transistor

FEATURES

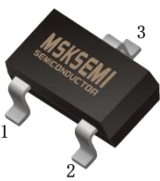
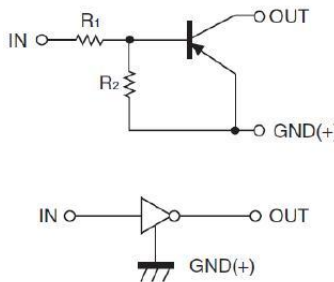

- Built-in resistors enable the configuration of a inverter circuit without connecting external input resistors.
- The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- Only the on/off conditions need to be set for operation, making device design easy.
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Weight: approx. 0.002g

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
V_{CC}	Supply Voltage	-50	V
V_{IN}	Input Voltage	-40 ~ +10	V
I_o	Output Current	-50	mA
I_{CM}	Peak Collector Current	-100	mA
P_D	Power Dissipation	150	mW
T_J	Junction to Ambient	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

These ratings are limiting values above which the serviceability of the device may be impaired

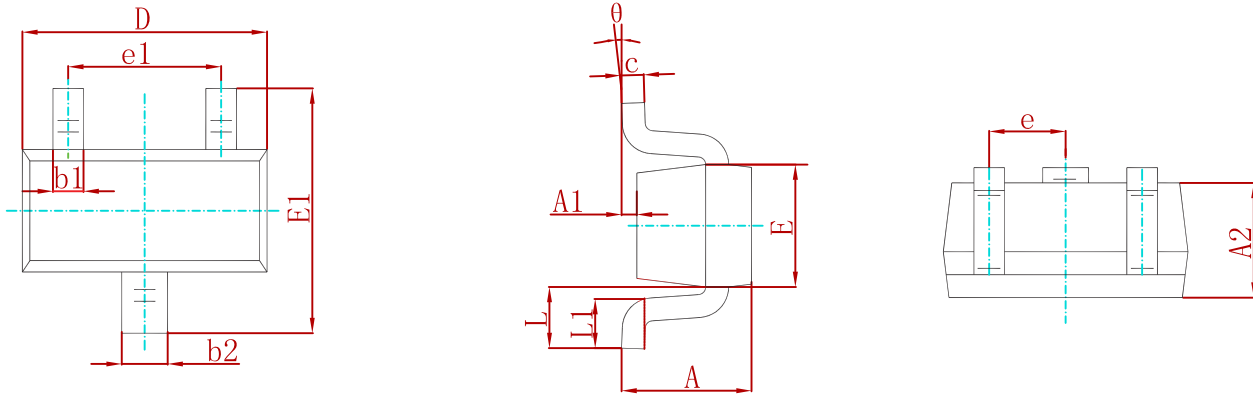
Reference News

Pin Configuration	ELECTRICAL SYMBOL	Marking
 <p>1.IN 2.GND 3.OUT</p>		
SOT-523		

Electrical Characteristics ($T_A = 25.0^\circ\text{C}$ unless otherwise noted)

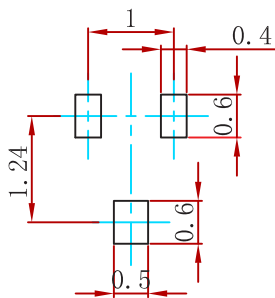
Parameter	Symbol	Test Condition	Limits			Unit
			Min	Typ	Max	
Input Voltage	$V_{I(off)}$	$V_{CC} = -5V, I_O = -100\mu A$	-0.5			V
	$V_{I(on)}$	$V_O = -0.3V, I_O = -10mA$			-3	V
Output Voltage	$V_{O(on)}$	$I_O / I_I = -10mA / -0.5mA$			-0.3	V
Input Current	I_I	$V_I = -5V$			-0.88	mA
Output Current	$I_{O(off)}$	$V_{CC} = -50V, V_I = 0$			-0.5	μA
DC Current Gain	G_I	$V_O = -5V, I_O = -5mA$	30			
Input Resistance	R_I		7	10	13	$K\Omega$
Resistance Ratio	R_2 / R_1		0.8	1	1.2	
Transition Frequency	f_T	$V_O = -10V, I_O = -5mA$ $f = 100MHz$		250		MHz

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DTA114EE(MS)	SOT-523	3000

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